molex

Vertical SMT Modular Jacks with Polyimide film for vacuum pick-and-place functionality can streamline high-volume PCB production and lower manufacturing costs

Automatic vacuum pick-and-place is the most common high-speed manufacturing process for precision placement of surface mount (SMT) components on printed circuit boards (PCBs) in mass production. The addition of Polyimide film to the surface of vertical SMT modular jacks facilitates automatic vacuum pick-and-place of the connector alongside other SMT components. This streamlines high-volume production and lowers manufacturing costs for customers. For additional information on Molex's complete offering of modular jacks visit: www.molex.com/product/modjacks.html

Features and Benefits

SMT vertical mounting with added Polyimide film	Automatic vacuum placement possible; lowers customer manufacturing costs
Polyimide film remains stable across a wide range of temperatures	Suitable for high-temperature SMT manufacturing; Polyimide film will keep its form, bond and integrity
Low-profile versions (series 85513) available	Allows for tight board stacking
RJ-11 and RJ-45 jacks available	Provides flexibility for variety of design applications
50µ" Gold plating options	Meets FCC68.5, IEC60603-7 and is approved for all FCC and IEC licenses applications
Palladium nickel (PdNi) + gold (Au) flash plating option	Achieves 2500 mating cycles; meets the new durability requirement of IEC60603-7 PL 2 and FCC68.5 standards

Applications

Networking

Servers Switches Routers

Commercial

Vending machines Cash registers Card swipes

Consumer

Set top boxes Home security Web TV Gaming devices

Office

Printers Photocopiers Desktops & laptops

Vertical SMT Modular Jacks with Polyimide Film

85510 Top Entry SMT Jacks 85513 Low Profile, Top Entry SMT Jacks



Vertical SMT Jack with Polyimide film



Network Switch



Commercial



Medical

Medical

Industrial

Bed monitors

Control units

Vision systems

Security systems Test equipment

Breathing devices

Home analysis monitors

molex

Specifications

REFERENCE INFORMATION

Packaging: Blister on Reels UL File No.: E107635 CSA File No.: N/A Mates With: Plugs, series 90075 RoHS: Yes Halogen Free: Yes Glow Wire Compliant: No

ELECTRICAL

Voltage (max.): 125V DC Current (max.): 1.5A Contact Resistance: 20 m Ω max. Dielectric Withstanding Voltage: 1000V rms Insulation Resistance: 500 M Ω min.

Ordering Information

Top Entry SMT Jacks

PHYSICAL

Housing:

LCP Fibre Glass Filled UL 94-VO Contact: Copper Alloy Plating: Contact Area —Gold or Gold flash over Palladium Nickel (PdNi) Underplating — Nickel (Ni) PCB Thickness: 1.57mm Operating Temperature: -40 to +85°C

Vertical SMT Modular Jacks with Polyimide Film

MECHANICAL

Contact Retention to Housing: 20 m Ω max. Insertion Force to PCB: 20N max. Mating Force: 20N max. Unmating Force: 20N max Durability (min.): 5,000 operations

Order No.	Housing Size	Circuits Loaded	Packaging	Туре	Solder Tabs	Mating Plugs
<u>85510</u> -5120	- 8	8	13" Reel	Top Entry SMT	Yes	90075 Series
85510-5128			22" Reel			
85510-5119	- 6	6	13" Reel			
85510-5127			22" Reel			
85510-5118	- 6	4	13" Reel			
85510-5126			22" Reel			
85510-5117	- 4	4	13" Reel			
85510-5125			22" Reel			

Low Profile, Top Entry SMT Jacks

Order No.	Housing Size	Circuits Loaded	Packaging	Туре	Mating Plugs
<u>85513</u> -5113	8	8	13" Reel	Low Profile Top Entry SMT	90075 Series
85513-5109	0		22" Reel		
85513-5114	G	6	13" Reel		
85513-5110	6		22" Reel		
85513-5115	6	4	13" Reel		
85513-5111	6		22" Reel		
85513-5116	4	4	13" Reel		
85513-5112	2 4		22" Reel		